

PCN Number:	20170116000	PCN Date:	Feb. 2, 2017
Title:	Datasheet for OPA314-Q1/OPA2314-Q1/OPA4314-Q1		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.



OPA314-Q1, OPA2314-Q1, OPA4314-Q1

SLOS896B – DECEMBER 2014 – REVISED JANUARY 2017

www.ti.com

Changes from Revision A (January 2015) to Revision B

Page

• Added part number OPA4314-Q1 to document	1
• Added part number OPA4314-Q1 to the <i>Device Information</i> table	1
• Changed OPA2314-Q1 package from SOIC (8) to VSSOP (8) in the <i>Device Information</i> table	1
• Added OPA314-Q1 (SOT-23 package) throughout document.....	3
• Added pinout drawing for the OPA4314-Q1 device in the <i>Pin Configurations and Functions</i> section	5
• Added the Pin Functions: OPA4314-Q1 table to the <i>Pin Configurations and Functions</i> section	5
• Changed formatting of all <i>Thermal Information</i> table notes	7
• Added footnotes to all <i>Thermal Information</i> tables.....	7
• Added <i>Thermal Information: OPA4314-Q1</i> table.....	9
• Changed formatting of application report reference in the <i>EMI Susceptibility and Input Filtering</i> section	20
• Changed package drawing to reflect an example of the 5-pin SOT-23 package in the <i>Layout Example</i> section	26
• Changed formatting of <i>Related Documentation</i> section	27
• Added part number OPA4314-Q1 to the <i>Related Links</i> table	27

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPA314-Q1/OPA2314-Q1/OPA4314-Q1	SLOS896A	SLOS896B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/lit/ds/symlink/opa4314-q1.pdf>

Reason for Change:

To accurately reflect device thermal characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

OPA2314AQDRQ1	OPA314AQDBVRQ1	OPA314AQDBVTQ1	OPA4314AQPWRQ1
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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